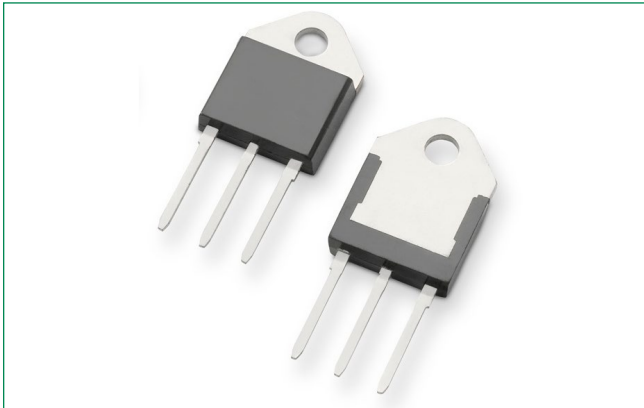


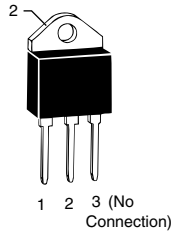
Pxxx0ME 5kA SIDACtor Series® in TO-218



Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation



Schematic Symbol



Description

The 5kA series SIDACtor® components are designed to protect equipment located in high exposure environments from severe overvoltage transients.

Setup in a robust TO-218 package, the 5kA series are ideal for use in data interface and AC power line for CATV amplifiers, Telecom Base Station equipment and Cell Towers.

Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade surge capability after multiple surge events within limit.
- Fails short circuit when surged in excess of rating
- Rugged TO-218 package
- 5000A 8/20 μ s surge rating
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- RoHS compliant, lead-free and halogen-free

Applicable Global Standards

- TIA-968-A
- TIA-968-B
- ITU K.20/21/45 Enhanced Level
- ITU K.20/21/45 Basic Level
- GR 1089 Intra-building
- IEC 61000-4-5 2nd Edition
- YD/T 1082
- YD/T 993
- YD/T 950
- GR 1089 Inter-building

Electrical Characteristics

Part Number	Marking	V_{DRM} @ $I_{DRM}=5\mu A$	V_S @ 100V/ μs	I_H	I_S	I_T	V_T @ $I_T=2.2 A$	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P1500MEL	P1500ME	140	180	50	800	2.2/25	4	400	650
P1900MEL	P1900ME	155	220	50	800	2.2/25	4	400	650
P2300MEL	P2300ME	180	260	50	800	2.2/25	4	350	600
P3800MEL	P3800ME	350	430	50	800	2.2/25	4	300	500
P4800MEL	P4800ME	450	600	20	800	2.2/25	4	300	500

Notes:
 - Absolute maximum ratings measured at $T_A=25^\circ C$ (unless otherwise noted).
 - Components are bi-directional (unless otherwise noted).
 - I_T is a free air rating and heat sink is at 25A

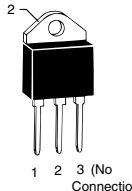
Surge Ratings

Series	I_{PP}			I_{TSM} 50 / 60 Hz	di/dt
	1.2/50 ¹ 8/20 ²	10/350 ¹ 1.2/50 ²	10/1000 ¹ 10/1000 ²		
	A min	A min	A min		
E	5000 ³	1500	1100	400	630

Notes:

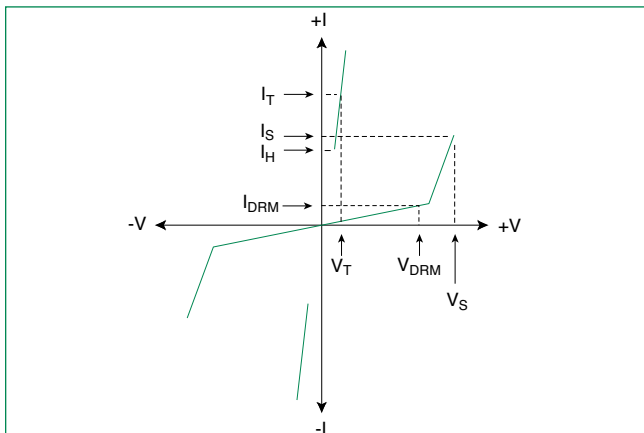
- 1 Voltage waveform in μs
 - 2 Current waveform in μs
 3. For surge rating of P3800MEL, it is minimum 4kA and typical 5kA @8/20 μs .
- Peak pulse current rating (I_{pp}) is repetitive and guaranteed for the life of the product.
 - The component must initially be in thermal equilibrium with $-40^{\circ}C \leq T_j \leq +150^{\circ}C$

Thermal Conditions

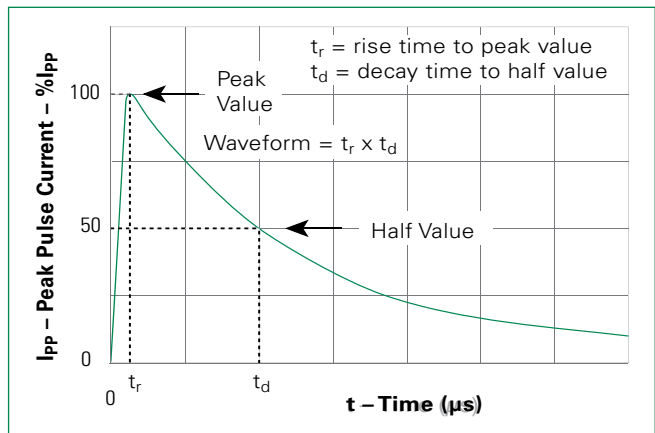
Package	Symbol	Parameter	Value	Unit
 TO-218	T_{j0}	Operating Junction Temperature Range	-40 to +150	$^{\circ}C$
	T_s	Storage Temperature Range	-65 to +150	$^{\circ}C$
	T_c	Maximum Case Temperature	100	$^{\circ}C$
	$R_{\theta JC}^*$	Thermal Resistance: Junction to Case	1.7	$^{\circ}C/W$
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	56	$^{\circ}C/W$

* $R_{\theta JC}$ rating assumes the use of a heat sink and on state mode for extended time at 25 A, with average power dissipation of 29.125 W.

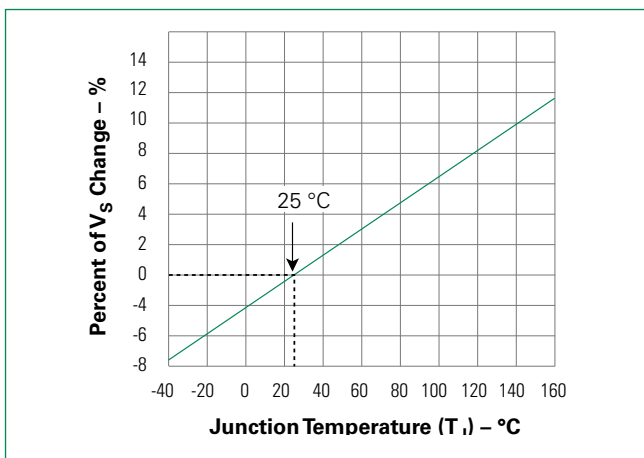
V-I Characteristics



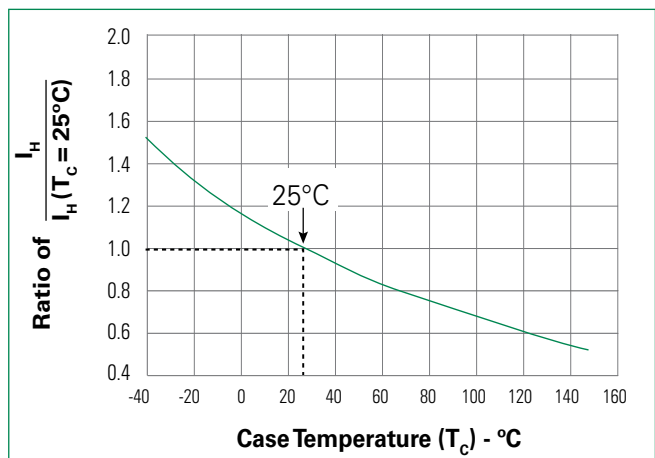
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

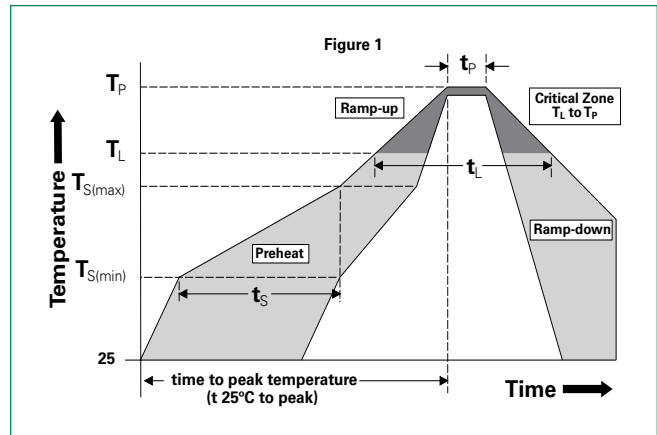


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	- Temperature Min ($T_{s(min)}$)	+150°C
	- Temperature Max ($T_{s(max)}$)	+200°C
	- Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	- Temperature (T_L) (Liquidus)	+217°C
	- Temperature (t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_p)		8 min. Max.
Do not exceed		+260°C



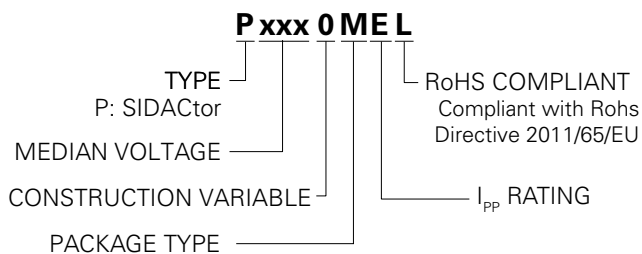
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification V-0

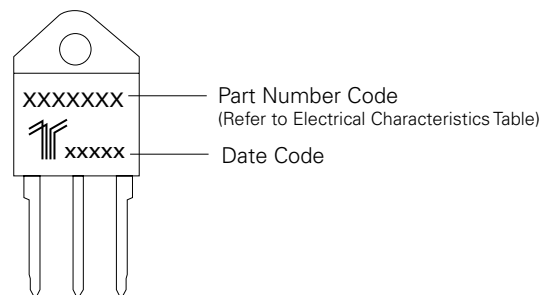
Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} ($V_{AC Peak}$) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

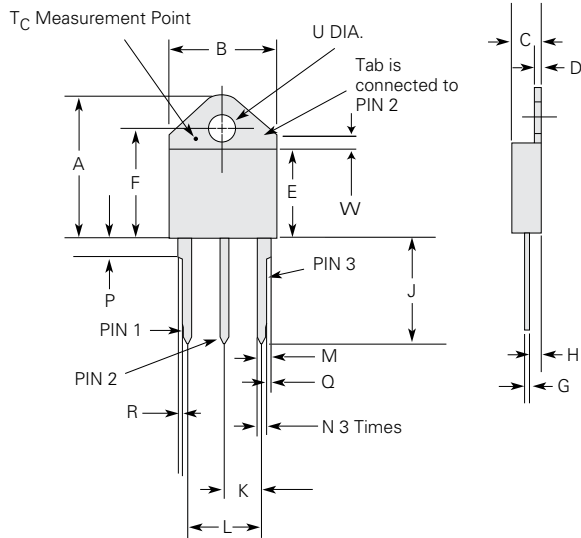
Part Numbering



Part Marking



Dimensions — TO-218



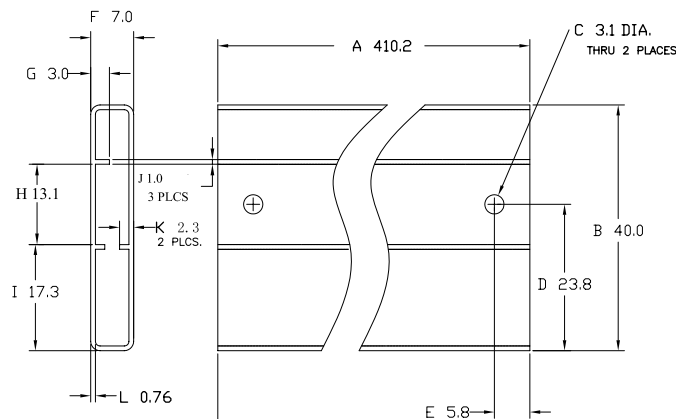
- Notes:**
- Mold flash shall not exceed 0.13 mm per side.
 - Maximum torque to be applied to mounting tab is 8 in-lbs. (0.904 Nm).
 - Pin 3 has no connection.
 - Tab is non-isolated (connects to middle pin).

Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.810	0.835	20.57	21.21
B	0.610	0.630	15.49	16.00
C	0.178	0.188	4.52	4.78
D	0.055	0.070	1.40	1.78
E	0.487	0.497	12.37	12.62
F	0.635	0.655	16.13	16.64
G	0.022	0.029	0.56	0.74
H	0.075	0.095	1.91	2.41
J	0.575	0.625	14.61	15.88
K	0.211	0.219	5.36	5.56
L	0.422	0.437	10.72	11.10
M	0.058	0.068	1.47	1.73
N	0.045	0.055	1.14	1.40
P	0.095	0.115	2.41	2.92
R	0.008	0.016	0.20	0.41
U	0.161	0.165	4.1	4.2
W	0.085	0.095	2.17	2.42

Packing Options

Package Type	Description	Packing Options Quantity	Added Suffix	Industry Standard
M	TO-218 (ME) Tube Pack	250(25 per tube/10 tubes per box)	N/A	N/A

Tube Pack Specification — TO-218



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